

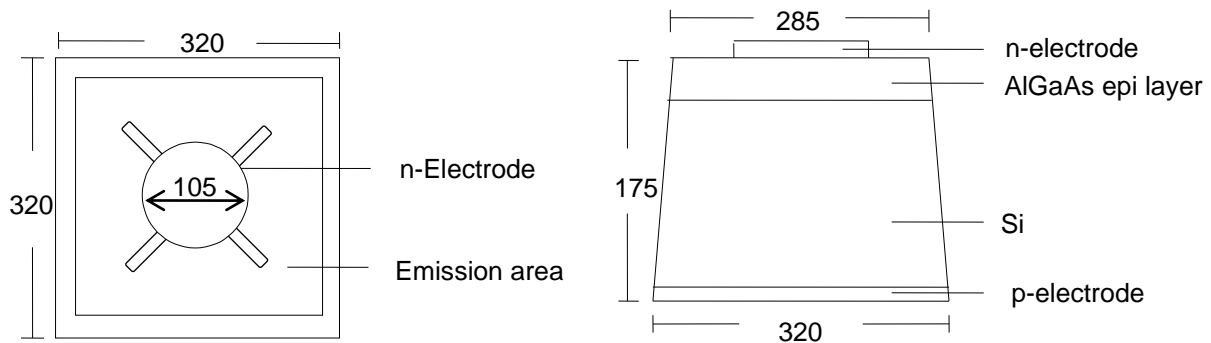
■ Features :

- Suitable for New Creative Products

■ Typical Applications :

- Home entertainment
- Light source for CMOS & CCD camera
- Security camera, CCTV

■ Outline Dimensions : (Unit: μm)



■ Physical Structure :

LED Chip dimension	Chip size	320 x 320 \pm 25 μm
	Thickness	175 \pm 25 μm
	Emission area	285 \pm 25 μm
	Bonding pad	105 \pm 10 μm
Electrode	Top: N (cathode)	Gold
	Backside: P (anode)	Gold
Surface condition	Frosted	

*C2

■ Electro-Optical Characteristics : ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward voltage	V_{FH}	$I_F = 100 \text{ mA}$	1.30	-	1.60	V
Reverse current	I_R	$V_R = 10\text{V}$	-	-	1	μA
Radiant Power	P_o	$I_F = 100 \text{ mA}$	14.0	-	24.0	mW
Wavelength	λ_P	$I_F = 100 \text{ mA}$	960		990	nm

■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

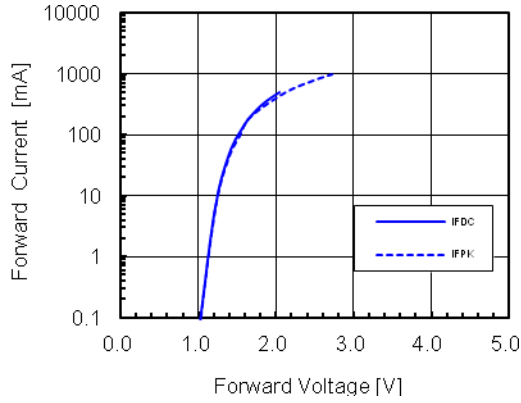


Fig 2. Relative Radiant Power vs. Wavelength

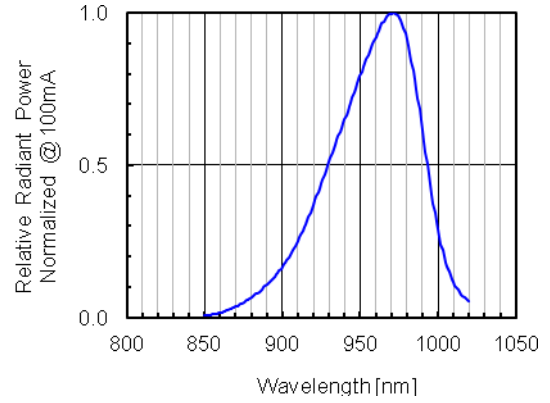


Fig 3. Relative Radiant Power vs. Forward DC Current

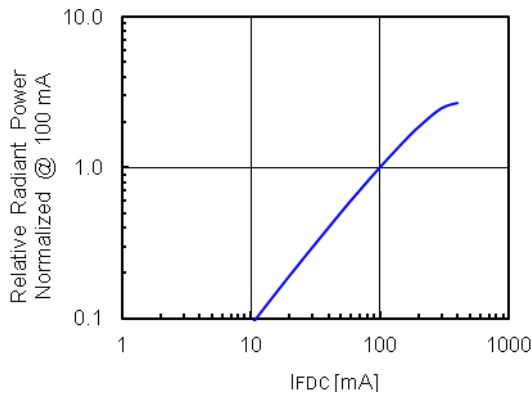


Fig 4. Relative Radiant Power vs. Forward Peak Current

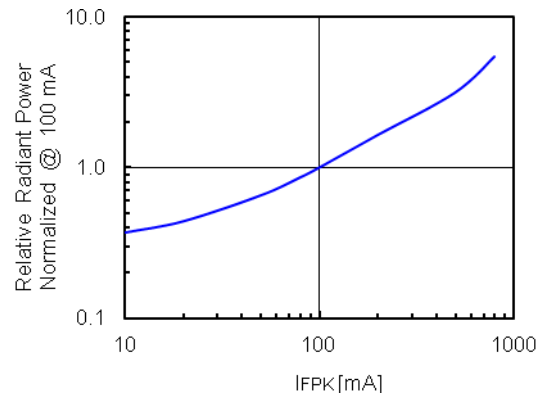


Fig 5. Forward DC Voltage vs. Temperature

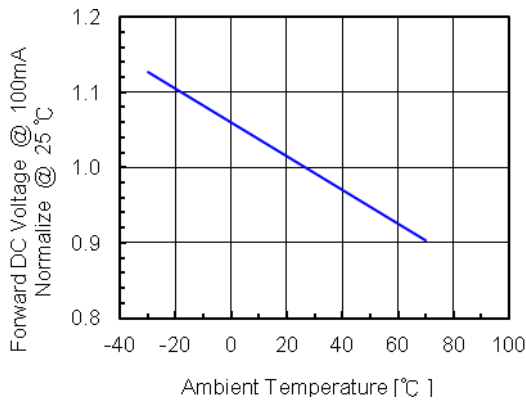


Fig 6. Relative Radiant Power vs. Temperature

